## Future Disruptions

### Opening Remarks by Session Chair



C. Rüster
Program Manager Funding Projects
ZEISS Semiconductor Manufacturing Technology,
Baden, Germany

**Abstract**
Coming Soon

**Biography**
Coming Soon

References

## Unlocking Public Funding for Strategic Semiconductor Projects



M. Isabelle
CEO & Founder
european economics, Paris, France

**Abstract**
The semiconductor industry is one of the largest beneficiaries of public funding in the EU. This momentum is reinforced by the **EU Chips Act 2.0** and **IPCEI AST**, which place semiconductor technologies and investments at the heart of Europe's renewed industrial policy. Grants support R&D activities, first industrial deployment of breakthrough innovations, and first-of-a-kind manufacturing facilities across the value chain. Securing State aid and EU funding remains highly competitive and requires a clear understanding of available opportunities, processes and regulations. Based on several use cases, Marc Isabelle's presentation will provide a practical first dive into public funding opportunities for the semiconductor industry in the EU.

**Biography**
Marc ISABELLE, engineer and PhD in Economics, is the founder and CEO of european economics.
Marc is a recognised expert in the public funding of strategic projects. Since 2009, he has helped 210 companies secure €46 billion in public funding for more than 250 major projects. These initiatives tackle key societal challenges - including disruptive innovation, decarbonisation, resilience and infrastructure - across a wide range of industrial sectors including microelectronics, software, telecoms, automotive, energy and environment, batteries, pharmaceuticals and biotech.
Through his extensive work with the European Commission and national authorities, Marc has actively contributed to shaping the methodologies and best practices used to assess public funding applications and their compatibility with EU regulations.

References

## Key building blocks for sustainable 6G networks (draft)



H. Kaib
Sustainability and Communication Manager
Nokia Solutions and Networks GmbH & Co. KG,
Ulm, Germany

**Abstract**
The presentation will cover energy-aware radio units and power amplifiers, AI-native baseband platforms for intelligent RAN, and smart software to reduce network power consumption while preserving performance and security (draft)

**Biography**
• Advocate for telecom's positive impact on people and planet.
• Over 30 years' experience in telecommunications in Europe, South America, and China in R&D, Business Development, Sales & Marketing.
• Dipl.-Ing. (FH) Allgemeine Elektrotechnik
• Dipl.-Wirt.Ing. (FH) Marketing (post-grad)
• Currently leads Sustainability and Communication, IPCEI ME/CT, Nokia Germany.

References

## Coming Soon

S. Kneitz
GlobalFoundries, Dresden, Germany



**Abstract**
Coming Soon

**Biography**
Coming Soon

References

**Designing Sustainable, Energy-Efficient and High-Performance Semiconductor Fabs**



S. Turtschan
Dipl. Ing. (FH), Director
Drees & Sommer SE, Center of Competence Semiconductor, Stuttgart, Germany

**Abstract**
The performance of a semiconductor fab is shaped long before production begins. Early decisions on factory layout, utilities, energy and resource concepts, modularization, automation and future expansion determine how efficiently and resiliently a fab can operate throughout its lifecycle.
This keynote explores an integrated approach to designing sustainable, energy-efficient and high-performance semiconductor fabs. It demonstrates how sustainability and operational efficiency can be embedded into fab planning through resource-efficient utility concepts, modular and scalable design, digital twins, automation and data-driven optimization. Particular attention is given to anticipating future disruptions, capacity expansions, changing equipment requirements and the challenges of both greenfield and brownfield environments.
By considering the fab as an integrated production system from the outset, sustainability, cost efficiency, operational performance and long-term adaptability can be addressed together rather than as separate objectives.

**Biography**
coming soon

References

**Shaping the future of non-volatile memories with the MRAM Alliance**



G. Lambinet
CCO
Hprobe, Eybens, France

**Abstract**
Over the past several decades, the semiconductor sector has been driven by Moore's Law, continuously increasing transistor density to improve chip performance. With computational power of AI chips having grown much faster than memory bandwidth and data transfer efficiency, data centers may soon be choked by the demand and the cost of providing high performance data access. At the same time, software-defined vehicles with centralized, high-compute chip architectures, need more bandwidth, faster boot times and persistent data for performance, safety, updateability, and user experience. Memory, once considered a commodity, is now left, right, and center.

Jump in MRAM! Magnetic Random Access Memory (MRAM) has become a compelling and widely deployed non-volatile memory technology across a growing range of applications spanning standalone and embedded products. With built-in persistence, near-infinite endurance, intrinsic robustness, faster read speed than DRAM, and better density than SRAM, MRAM is now poised to expand into next-generation automotive, storage and AI systems.

MRAM however stands at a critical juncture. Despite technical readiness and availability at tier-1 foundries (TSMC, Samsung and GF leading the pack), adoption still faces hesitation. Fragmented efforts, slow standardization, and inconsistent messaging hinder progress. This triggered stakeholders across the whole value chain, from foundries to chip makers, IP vendors and system companies, equipment suppliers and leading universities/research centers, to join forces. SNIA's MRAM Alliance Special Interest Group (SIG) is designed to align the industry on key priorities, address real-world challenges, improve education and awareness, create standards when applicable, facilitate product implementation, and ultimately maximize end-system product benefits.

Whether you're ready to deploy today or want to help shape what comes next, come hear what's not to love about MRAM, and how the MRAM Alliance can shape the future.

**Biography**
Gilles Lambinet is an international sales and business development executive with more than 25 years of experience in high-technology industries. An engineer by background, he graduated from ENSAM Paris (École Nationale Supérieure d'Arts et Métiers) and holds an MBA from Purdue University. He is particularly passionate about emerging technologies and innovation and combines strong technical expertise with a proven track record in turning complex technologies into successful business opportunities.
Throughout his career, he has worked with and for multiple technology companies, developing markets and driving international growth across diverse industries. His experience spans industrial automation, robotics, automotive, glass manufacturing, IT, utilities, digital technologies and semiconductors. A significant part of his career was spent at Hewlett-Packard, where he held international leadership positions across sales, marketing and supply-chain activities in EMEA. He subsequently moved into entrepreneurship and business development, supporting innovative technology companies in their go-to-market strategies and international expansion. His later activities covered emerging fields including cloud, IoT, digital transformation, data science and artificial intelligence.
Today, as Chief Commercial Officer of Hprobe, he is focused on the semiconductor industry and advanced

automated test equipment for magnetic devices. His current role places him at the forefront of a strategic high-tech ecosystem, working with semiconductor companies and technology partners worldwide.

References

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